

# MECHANICAL CASE OUTLINE

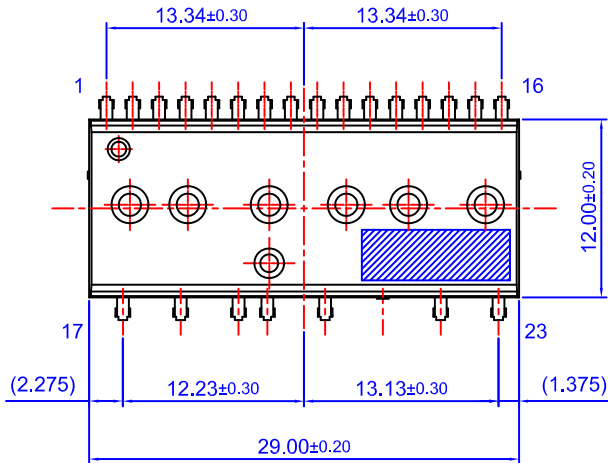
## PACKAGE DIMENSIONS

ON Semiconductor®



SPM5E-023 / 23LD, PDD STD, FULL PACK, DIP TYPE  
CASE MODEJ  
ISSUE O

DATE 31 JAN 2017



NOTES: UNLESS OTHERWISE SPECIFIED  
A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD  
B) ALL DIMENSIONS ARE IN MILLIMETERS  
C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS  
D) ( ) IS REFERENCE

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